onsemi

Single Inverter with Open Drain Output

NL17SZ06

The NL17SZ06 is a single inverter with open drain output in tiny footprint packages.

Features

- Designed for 1.65 V to 5.5 V V_{CC} Operation
- 2.1 ns t_{PD} at $V_{CC} = 5 V (typ)$
- Input/Output Overvoltage Tolerant up to 5.5 V
- IOFF Supports Partial Power Down Protection
- Source/Sink 24 mA at 3.0 V
- Available in SC-88A, SC-74A, SOT-553, SOT-953 and UDFN6 Packages
- Chip Complexity < 100 FETs
- NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

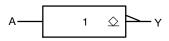
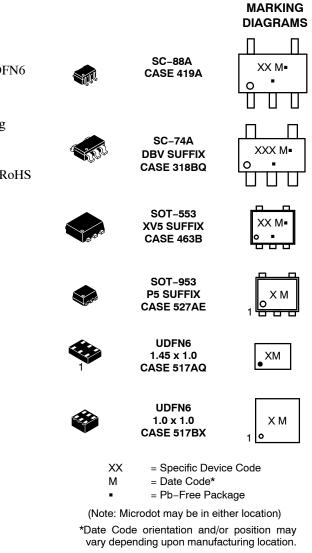


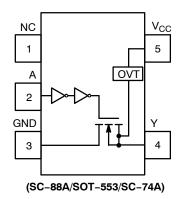
Figure 1. Logic Symbol

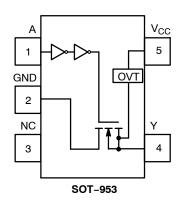


ORDERING INFORMATION

See detailed ordering, marking and shipping information in the package dimensions section on page 7 of this data sheet.

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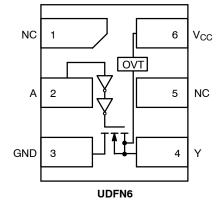


Figure 2. Pinout (Top View)

PIN ASSIGNMENT

(SC-88A/SOT-553/SC-74A)

Pin	Function
1	NC
2	A
3	GND
4	Y
5	V _{CC}

PIN ASSIGNMENT (SOT-953)

Pin	Function
1	А
2	GND
3	NC
4	Y
5	V _{CC}

PIN ASSIGNMENT (UDFN)

Pin	Function
1	NC
2	A
3	GND
4	Y
5	NC
6	V _{CC}

FUNCTION TABLE

A Input	Y Output
L	Z
Н	L

MAXIMUM RATINGS

Symbol	CI	naracteristics	Value	Unit
V_{CC}	DC Supply Voltage	SC-88A (NLV) C-74A, SC-88A, SOT-553, SOT-953, UDFN6	-0.5 to +7.0 -0.5 to +6.5	V
V _{IN}	DC Input Voltage SC	SC-88A (NLV) C-74A, SC-88A, SOT-553, SOT-953, UDFN6	-0.5 to +7.0 -0.5 to +6.5	V
V _{OUT}	DC Output Voltage SC-88A (NLV)	Active-Mode (High or Low State) Tri-State Mode (Note 1) Power-Down Mode (V _{CC} = 0 V)	-0.5 to V _{CC} + 0.5 -0.5 to +7.0 -0.5 to +7.0	V
	DC Output Voltage SC-74A, SC-88A, SOT-553, SOT-953, UDFN6	Active-Mode (High or Low State) Tri-State Mode (Note 1) Power-Down Mode (V _{CC} = 0 V)	$\begin{array}{c} -0.5 \text{ to } V_{CC} + 0.5 \\ -0.5 \text{ to } +6.5 \\ -0.5 \text{ to } +6.5 \end{array}$	V
I _{IK}	DC Input Diode Current	V _{IN} < GND	-50	mA
I _{OK}	DC Output Diode Current	V _{OUT} < GND	-50	mA
I _{OUT}	DC Output Source/Sink Current	±50	mA	
I _{CC} or I _{GND}	DC Supply Current per Supply Pin	±100	mA	
T _{STG}	Storage Temperature Range		-65 to +150	°C
ΤL	Lead Temperature, 1 mm from Ca	se for 10 secs	260	°C
ТJ	Junction Temperature Under Bias		+150	°C
θ_{JA}	Thermal Resistance (Note 2)	SC-88A SC-74A SOT-553 SOT-953 UDFN6	377 320 324 254 154	°C/W
P _D	Power Dissipation in Still Air	SC-88A SC-74A SOT-553 SOT-953 UDFN6	332 390 386 491 812	mW
MSL	Moisture Sensitivity		Level 1	-
F _R	Flammability Rating	Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in	-
V_{ESD}	ESD Withstand Voltage (Note 3)	Human Body Model Charged Device Model	2000 1000	V
I _{Latchup}	Latchup Performance (Note 4)		±100	mA

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.
Applicable to devices with outputs that may be tri-stated.
Measured with minimum pad spacing on an FR4 board, using 10mm-by-1inch, 2 ounce copper trace no air flow per JESD51-7.
HBM tested to ANSI/ESDA/JEDEC JS-001-2017. CDM tested to EIA/JESD22-C101-F. JEDEC recommends that ESD qualification to EIA/JESD22-A115-A (Machine Model) be discontinued per JEDEC/JEP172A.
Tested to EIA/JESD78 Class II.

RECOMMENDED OPERATING CONDITIONS

Symbol	Chara	cteristics	Min	Max	Unit
V _{CC}	Positive DC Supply Voltage		1.65	5.5	V
V _{IN}	DC Input Voltage		0	5.5	V
V _{OUT}	DC Output Voltage	Active-Mode (High or Low State) Tri-State Mode (Note 1) Power-Down Mode (V _{CC} = 0 V)	0 0 0	V _{CC} 5.5 5.5	
T _A	Operating Temperature Range		-55	+125	°C
t _r , t _f	Input Rise and Fall Time SC-88A (NLV)	V_{CC} = 3.0 V to 3.6 V V_{CC} = 4.5 V to 5.5 V	0 0	100 20	ns/V
	Input Rise and Fall Time SC-74A, SC-88A, SOT-553, SOT-953, UDFN6	$\begin{array}{c} V_{CC} = 1.65 \ V \ to \ 1.95 \ V \\ V_{CC} = 2.3 \ V \ to \ 2.7 \ V \\ V_{CC} = 3.0 \ V \ to \ 3.6 \ V \\ V_{CC} = 4.5 \ V \ to \ 5.5 \ V \end{array}$	0 0 0 0	20 20 10 5	

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

DC ELECTRICAL CHARACTERISTICS

			Vcc	T	A = 25°	С	–55°C ≤ T _A ≤ 125°C		
Symbol	Parameter	Condition	(V)	Min	Тур	Max	Min	Max	Units
V _{IH}	High-Level Input		1.65 to 1.95	0.75 x V _{CC}	-	-	0.75 x V _{CC}	-	V
	Voltage (NLV)		2.3 to 5.5	$0.70 \times V_{CC}$	-	-	$0.70 \times V_{CC}$	-	
	High-Level Input		1.65 to 1.95	$0.65 \times V_{CC}$	-	-	$0.65 \times V_{CC}$	-	V
	Voltage		2.3 to 5.5	0.70 x V _{CC}	-	-	0.70 x V _{CC}	-	
V _{IL}	Low-Level Input		1.65 to 1.95	-	-	$0.25 \times V_{CC}$	-	$0.25 \times V_{CC}$	V
	Voltage (NLV)		2.3 to 5.5	-	-	$0.30 \times V_{CC}$	-	$0.30 \times V_{CC}$	
	Low-Level Input		1.65 to 1.95	_	-	0.35 x V _{CC}	-	0.35 x V _{CC}	V
	Voltage		2.3 to 5.5	-	-	$0.30 \times V_{CC}$	-	$0.30 \times V_{CC}$	
V _{OL}	Low-Level Output Voltage		1.65 to 5.5 1.65 2.3 2.7 3.0 3.0 4.5	- - - - -	0.08 0.2 0.22 0.28 0.38 0.42	0.1 0.24 0.3 0.4 0.4 0.55 0.55		0.1 0.24 0.3 0.4 0.4 0.55 0.55	V
I _{IN}	Input Leakage Cur- rent	V _{IN} = 5.5 V or GND	1.65 to 5.5	-	-	±0.1	-	±1.0	μΑ
I _{OZ}	3-State Output Leakage Current	V _{OUT} = 0 V to 5.5 V	1.65 to 5.5	-	-	±0.5	-	±5.0	μΑ
I _{OFF}	Power Off Leakage Current	V _{IN} = 5.5 V or V _{OUT} = 5.5 V	0	-	-	1.0	-	10	μΑ
I _{CC}	Quiescent Supply Current	$V_{IN} = V_{CC}$ or GND	5.5	-	-	1.0	-	10	μΑ

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

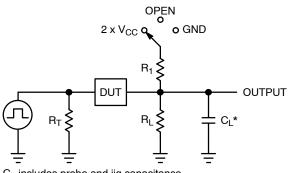
AC ELECTRICAL CHARACTERISTICS

			V _{CC}	T,	₄ = 25°	С	–55°C ≤ T	_A ≤ 125°C	
Symbol	Parameter	Condition	(V)	Min	Тур	Max	Min	Мах	Units
t _{PZL}	Propagation Delay,		1.65 to 1.95	-	6.0	9.0	-	9.5	ns
	A to Y (Figures 3 and 4)		2.3 to 2.7	-	3.6	6.1	-	6.5	
			3.0 to 3.6	-	2.7	5.6	-	6.0	
			4.5 to 5.5	-	2.1	4.4	-	4.8	
t _{PLZ}	Propagation Delay,		1.65 to 1.95	-	4.0	9.0	-	9.5	ns
	A to Y (Figures 3 and 4)		2.3 to 2.7	-	2.8	6.1	-	6.5	
			3.0 to 3.6	-	2.5	5.6	-	6.0	
			4.5 to 5.5	-	2.2	4.4	-	4.8	

CAPACITIVE CHARACTERISTICS

Symbol	Parameter	Condition	Typical	Units
C _{IN}	Input Capacitance	V_{CC} = 5.5 V, V_{IN} = 0 V or V_{CC}	2.5	pF
C _{OUT}	Output Capacitance	V_{CC} = 5.5 V, V_{IN} = 0 V or V_{CC}	2.5	pF
C _{PD}	Power Dissipation Capacitance (Note 5)	10 MHz, V _{CC} = 3.3 V, V _{IN} = 0 V or V _{CC} 10 MHz, V _{CC} = 5.5 V, V _{IN} = 0 V or V _{CC}	9 11	pF

5. C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: $I_{CC(OPR)} = C_{PD} \bullet V_{CC} \bullet f_{in} + I_{CC}$. C_{PD} is used to determine the no–load dynamic power consumption; $P_D = C_{PD} \bullet V_{CC}^2 \bullet f_{in} + I_{CC} \bullet V_{CC}$.

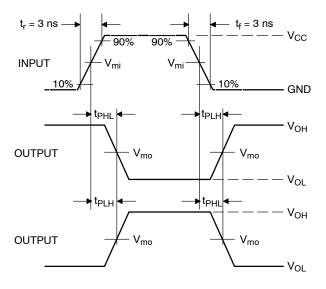


Position	С _L , рF	R_{L}, Ω	R ₁ , Ω		
Open	See AC Characteristics Table				
$2 \times V_{CC}$	50	500	500		
GND	50	500	500		
	Open 2 x V _{CC}	Open See AC Character 2 x V _{CC} 50 GND 50	OpenSee AC Characteristics Tab2 x V _{CC} 50GND5050500		

X = Don't Care

 C_L includes probe and jig capacitance R_T is Z_{OUT} of pulse generator (typically 50 $\Omega)$ f = 1 MHz

Figure 3. Test Circuit



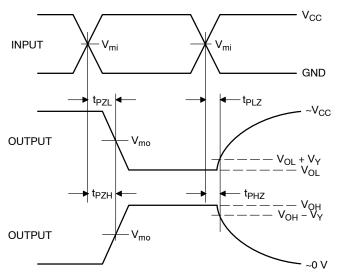


Figure 4. Switching Waveforms

		Vm		
V _{CC} , V	V _{mi} , V	t _{PLH} , t _{PHL}	t _{PZL} , t _{PLZ} , t _{PZH} , t _{PHZ}	V _Y , V
1.65 to 1.95	V _{CC} /2	V _{CC} /2	V _{CC} /2	0.15
2.3 to 2.7	V _{CC} /2	V _{CC} /2	V _{CC} /2	0.15
3.0 to 3.6	V _{CC} /2	V _{CC} /2	V _{CC} /2	0.3
4.5 to 5.5	V _{CC} /2	V _{CC} /2	V _{CC} /2	0.3

DEVICE ORDERING INFORMATION

Device	Packages	Specific Device Code	Pin 1 Orientation (See below)	Shipping [†]
NL17SZ06DFT2G	SC-88A	LF	Q4	3000 / Tape & Reel
NLV17SZ06DFT2G*	SC-88A	LF	Q4	3000 / Tape & Reel
NL17SZ06DBVT1G	SC-74A	AF	Q4	3000 / Tape & Reel
NL17SZ06XV5T2G	SOT-553	LF	Q4	4000 / Tape & Reel
NL17SZ06XV5T2G-L22087**	SOT-553	LF	Q4	4000 / Tape & Reel
NL17SZ06P5T5G (In Development)	SOT-953	TBD	Q2	8000 / Tape & Reel
NL17SZ06MU1TCG (In Development)	UDFN6, 1.45 x 1.0, 0.5P	TBD	Q4	3000 / Tape & Reel
NL17SZ06MU3TCG (In Development)	UDFN6, 1.0 x 1.0, 0.35P	TBD	Q4	3000 / Tape & Reel

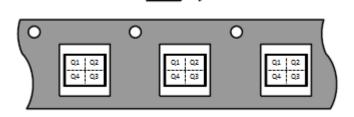
†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

*NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC–Q100 Qualified and PPAP Capable.

** Please refer to NLV specifications for this device.

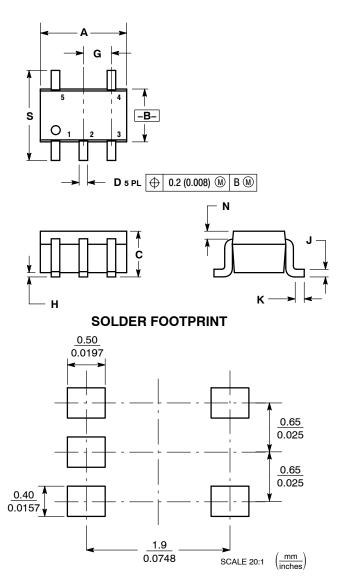
Pin 1 Orientation in Tape and Reel

Direction of Feed



PACKAGE DIMENSIONS

SC-88A (SC-70-5/SOT-353) CASE 419A-02 ISSUE L

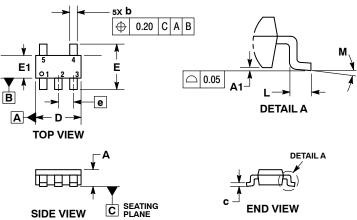


NOTES:
 DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 CONTROLLING DIMENSION: INCH.
 419A-01 OBSOLETE. NEW STANDARD 419A-02.
 DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
Α	0.071	0.087	1.80	2.20
В	0.045	0.053	1.15	1.35
С	0.031	0.043	0.80	1.10
D	0.004	0.012	0.10	0.30
G	0.026 BSC		0.65 BSC	
Н		0.004		0.10
ſ	0.004	0.010	0.10	0.25
К	0.004	0.012	0.10	0.30
Ν	0.008 REF		0.20 REF	
S	0.079	0.087	2.00	2.20

PACKAGE DIMENSIONS

SC-74A CASE 318BQ **ISSUE B**



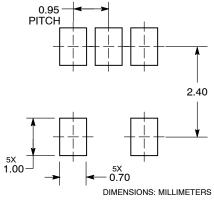
С **END VIEW** NOTES:

- NOTES:
 DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 CONTROLLING DIMENSION: MILLIMETERS.
 MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
 DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.15 PER SIDE.

EXCEED 0.15 FER SIDE				
	MILLIMETERS			
DIM	MIN MAX			
Α	0.90	1.10		
A1	0.01	0.10		
b	0.25	0.50		
С	0.10	0.26		
D	2.85	3.15		
Е	2.50 3.00			
E1	1.35	1.65		
е	0.95 BSC			
L	0.20	0.60		
м	0 °	10 °		

RECOMMENDED SOLDERING FOOTPRINT*

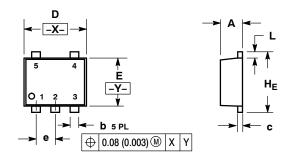
SIDE VIEW



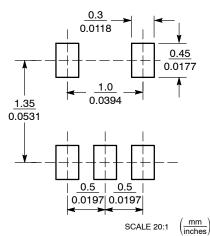
*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

SOT-553, 5 LEAD CASE 463B **ISSUE C**



RECOMMENDED SOLDERING FOOTPRINT*



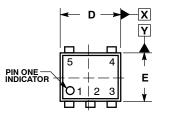
*For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: MILLIMETERS 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

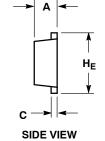
	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.50	0.55	0.60	0.020	0.022	0.024
b	0.17	0.22	0.27	0.007	0.009	0.011
С	0.08	0.13	0.18	0.003	0.005	0.007
D	1.55	1.60	1.65	0.061	0.063	0.065
Е	1.15	1.20	1.25	0.045	0.047	0.049
е	0.50 BSC			0.020 BSC		
L	0.10	0.20	0.30	0.004	0.008	0.012
HE	1.55	1.60	1.65	0.061	0.063	0.065

PACKAGE DIMENSIONS

SOT-953 CASE 527AE ISSUE E

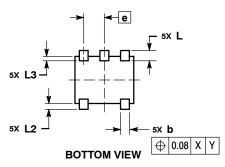


TOP VIEW

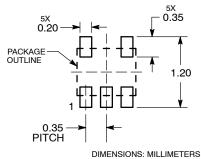


- NOTES: 1. DIMENSIONING AND TOLERANCING PER ASME
- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 CONTROLLING DIMENSION: MILLIMETERS
 MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL.
 DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

	MILLIMETERS			
DIM	MIN	NOM	MAX	
Α	0.34	0.37	0.40	
b	0.10	0.15	0.20	
С	0.07	0.12	0.17	
D	0.95	1.00	1.05	
Е	0.75	0.80	0.85	
e	0.35 BSC			
HE	0.95	1.00	1.05	
Г	0.175 REF			
L2	0.05	0.10	0.15	
L3			0.15	



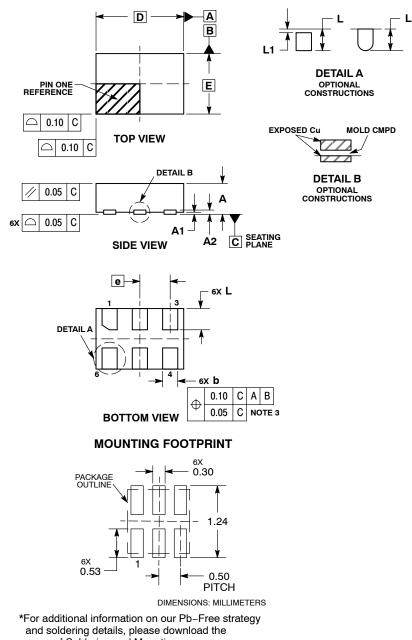
SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

UDFN6, 1.45x1.0, 0.5P CASE 517AQ ISSUE O



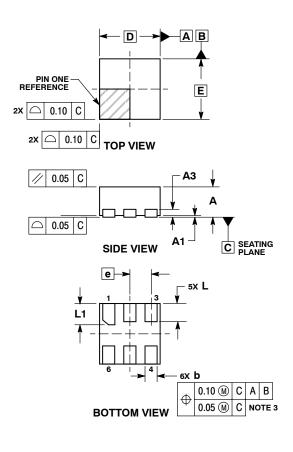
onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

NOTES:
 DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 CONTROLLING DIMENSION: MILLIMETERS.
 DIMENSION & APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM THE TERMINAL TIP.

	MILLIMETERS		
DIM	MIN	MAX	
Α	0.45	0.55	
A1	0.00 0.05		
A2	0.07 REF		
b	0.20	0.30	
D	1.45 BSC		
Е	1.00 BSC		
е	0.50 BSC		
L	0.30	0.40	
L1		0.15	

PACKAGE DIMENSIONS

UDFN6, 1x1, 0.35P CASE 517BX ISSUE O

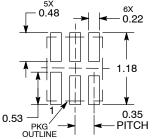


NOTES: 1. DIMENSIONING AND TOLERANCING PER ASME Y14 5M 1994

- ASME Y14.5M, 1994. 2. CONTROLLING DIMENSION: MILLIMETERS. 3. DIMENSION & APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN
- TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.20 MM FROM TERMINAL TIP. 4. PACKAGE DIMENSIONS EXCLUSIVE OF

Ì	BURRS AND MOLD FLASH				
		MILLIN			
	DIM	MIN			
	Α	0.45	0.55		
	A1	0.00	0.05		
	A3	0.13			
	b	0.12	0.22		
	D	1.00			
	Е	1.00			
	е	0.35			
	L	0.25	0.35		
	L1	0.30	0.40		

RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb–Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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